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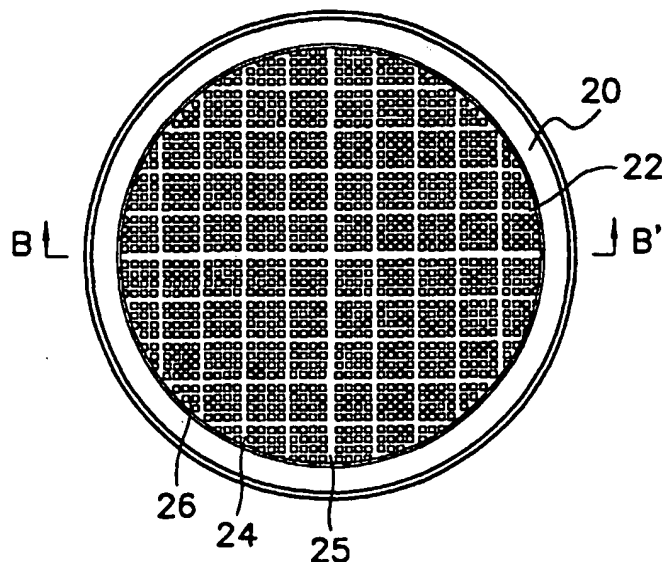
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(54) Title: CONDITIONER FOR POLISHING PAD AND METHOD FOR MANUFACTURING THE SAME



(57) Abstract: A conditioner for polishing pad and a method for manufacturing the same are disclosed. The conditioner comprises a substrate having formed with a plurality of geometrical protrusions of a uniform height on at least one of its sides, and a cutting portion having a diamond layer of a uniform thickness formed substantially on a whole surface of the side of the substrate having the geometrical protrusions. The geometrical protrusions have a flat upper surface or the upper surface may comprise a plurality of smaller geometrical protrusions formed by recessed grooves. The substrate is made from ceramic or cemented carbide materials and has a shape of a disk, a plate having multiple corner, a cup, a segment, or a doughnut with flattened upper and lower surfaces. The conditioner may further comprise a body portion being fixedly attached to the substrate at a side opposite to the side having formed with geometrical protrusions for linking the cutting portion to conditioning equipment. The cutting portion of the conditioner realized by having above shapes and structures makes

line and surface contacts with polishing pad surface. The diamond layer coated on the cutting surface strengthens the structural integrity of the cutting surface to increase the cutting performance and imparts antiwear and anti-corrosive properties to render the conditioner with a prolonged lifetime usage.

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